

[제23회] 한국반도체학술대회_Program at a Glance

2월 22일(월)	Room A 태백홀(5층)	Room B 함백홀(5층)
14:00-18:00	[Short Course 1] 3차원 집적 기술: 원리와 응용	[Short Course 2] 차세대 저전력소자의 개발과 설계

2월 23일(화)	Room A	Room B	Room C	Room D	Room E	Room F	Room G	Room H	Room I	Room J	Room K	Room L	
	5층				6층								
	태백I	태백II+III	함백I	함백II+III	컨벤션홀L	봉래I	봉래II+III	육백I	육백II	청옥I	청옥II+III	5층 로비	
08:30-10:30	[TA1-L] Analog Design I	[TB1-D] 1D/2D Materials & Devices	[TC1-F] Novel Si Devices and Integrated Circuits (4)	[TD1-G] Device Physics and Characterization 1 : Field-effect		[TF1-I] High efficiency sensors and devices	[TG1-F] Novel Si Devices and Integrated Circuits (1)	[TH1-J] Nanofabrication for Application	CDC	[TJ1-K] Memory processing and RRAM operation	[TK1-R] Interaction of system SW and semiconductor	Chip Design Contest & 전시	
10:30-10:40	휴식 (& 커피, 다과)												
10:40-12:40	[TA2-L] Analog Design II	[TB2-D] Oxide Semiconductors	[TC2-M] RFIC and smart RFID tags	[TD2-G] Reliability Analysis : Thin-film transistors and field-effect transistors		[TF2-O] VLSI System Design for Communications	[TG2-F] Novel Si Devices and Integrated Circuits (2)	[TH2-J] Nanofabrication for Application		[TJ2-K] NAND, PCRAM, and MRAM	[TK2-R] Little more faster, and even better reliability		
12:40-13:40	점심 [포레스트볼룸 / 4층]												
13:40-14:20	기조강연 1 : Prof. Akira Toriumi (The University of Tokyo) "Materials Innovation for Versatile Electron Devices in IoT Era" [컨벤션홀 K+W / 5층]												
14:20-15:00	기조강연 2 : 박재근 교수 (한양대학교) " Nonvolatile Memory Technology beyond 20nm : Dilemma & Challenge" [컨벤션홀 K+W / 5층]												
15:00-15:10	휴식 (& 커피, 다과)												
15:10-17:10	[TA3-A] A2: Enabling packaging technologies	[TB3-D] Process Technology for Thin Films	[TC3-H] Display and Imaging Technologies	[TD3-G] Device Modeling and Simulation 1 : RF, terahertz, low-power, and		[TF3-Q] Metrology and Inspection I	[TG3-F] Novel Si Devices and Integrated Circuits (3)	[TH3-J] Graphene and Related Carbon Nanostructures	[TI1-N] Advances in Design Technology	[TJ3-K] Circuit related topics and memory selectors	[TK3-E] Advanced GaN Technology		
17:10-18:30					포스터 세션1 [TP1]								
18:30-20:00	만찬 [컨벤션홀 K+W / 5층]												
20:00-	Rump Session 1 : 스케일링 한계 극복을 위한 미래 반도체 기술 [태백홀 / 5층] Rump Session 2 : 초연결 사회의 반도체 기술 전망과 과제 [함백홀 / 5층]												

2월 24일(수)	Room A	Room B	Room C	Room D	Room E	Room F	Room G	Room H	Room I	Room J	Room K	Room L
	5층				6층							
	태백I	태백II+III	함백I	함백II+III	컨벤션홀L	봉래I	봉래II+III	육백I	육백II	청옥I	청옥II+III	5층 로비
08:30-10:00	[WA1-A] A1: Contact and thin film technologies for high performance	[WB1-D] Thin Films for Emerging Devices I	[WC1-C] Materials Growth & Characterization : Emerging new electrical	[WD1-G] Device Physics and Characterization 2 : Memory devices		[WF1-Q] Metrology and Inspection II	[WG1-F] Materials and Processing Technologies	[WH1-J] Two-Dimensional Materials beyond Graphene	[WI1-N] Architecture-Level Design Techniques	[WJ1-K] Unconventional approaches in memory research	[WK1-E] GaN Power Device	전시
10:00-10:10	휴식 (& 커피, 다과)											
10:10-11:40	[WA2-A] A3: Novel interconnect and packaging technologies for emerging	[WB2-D] Thin Films for Emerging Devices II	[WC2-C] Materials Growth & Characterization : III-Nitrides and Si	[WD2-G] Device Modeling and Simulation 2 : Ab-initio and theoretical study		[WF2-O] VLSI System Design and Applications	[WG2-F] Si and Group-IV Photonics	[WH2-J] Two-Dimensional Materials / Spintronics	[WI2-B] Patterning	[WJ2-P] Device for Energy (Solar Cell, Power Device, Battery, etc.)	[WK2-E] III-V Device	
11:40-13:00					포스터 세션2 [WP1]							
13:00-	점심 [포레스트볼룸 / 4층]											